SOT26 (E) Package Outline Drawing

NOTES:
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
4. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

<table>
<thead>
<tr>
<th>Part Number Suffix</th>
<th>Package Body Material</th>
<th>Lead Finish</th>
<th>MSL Rating</th>
<th>Package Marking[^3][^4]</th>
</tr>
</thead>
<tbody>
<tr>
<td>RoHS Compliant Mold Compound</td>
<td>Sn/Pb Solder</td>
<td>MSL1[^1]</td>
<td>HNNN XXXX</td>
<td></td>
</tr>
<tr>
<td>E</td>
<td>RoHS Compliant Mold Compound</td>
<td>100% matte Sn</td>
<td>MSL1[^2]</td>
<td>NNNE XXXX</td>
</tr>
</tbody>
</table>

[^1]: Max peak reflow temperature of 235 °C
[^2]: Max peak reflow temperature of 260 °C
[^3]: 4-Digit lot number XXXX
[^4]: 3-Digit part number NNN

For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373
Order On-line at www.hittite.com
Suggested SOT26 (E) PCB Land Pattern

NOTES:
1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.